

# CSPESD304

## 4-Channel ESD Array in CSP

### Product Description

The CSPESD304 is a quad ESD transient voltage suppression diode array. Each diode provides a very high level of protection for sensitive electronic components that may be subjected to electrostatic discharge (ESD). These diodes safely dissipate ESD strikes of  $\pm 15$  kV, exceeding the maximum requirement of the IEC 61000-4-2 international standard. Using the MIL-STD-883 (Method 3015) specification for Human Body Model (HBM) ESD, the device provides protection for contact discharges to greater than  $\pm 30$  kV.

The CSPESD304 is particularly well-suited for portable electronics (e.g., cellular telephones, PDAs, notebook computers) because of its small package and low weight.

The CSPESD304 is available in a space-saving, low-profile Chip Scale Package with lead-free finishing.

### Features

- Four Channels of ESD Protection
- $\pm 15$  kV ESD Protection on each Channel (IEC 61000-4-2 Level 4, Contact Discharge)
- $\pm 30$  kV ESD Protection on each Channel (HBM)
- Chip Scale Package Features Extremely Low Lead Inductance for Optimum ESD Protection
- 5-Bump, 0.960 mm x 1.330 mm Footprint Chip Scale Package (CSP)
- These Devices are Pb-Free and are RoHS Compliant

### Applications

- ESD Protection for Sensitive Electronic Equipment
- I/O Port and Keypad and Button Circuitry Protection for Portable Devices
- Can be Used for EMI Filtering when Combined with External Series Resistance
- Wireless Handsets
- Handheld PCs / PDAs
- MP3 Players
- Digital Camcorders
- Notebooks
- Desktop PCs



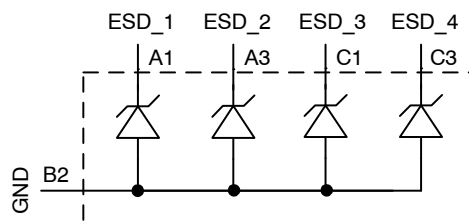
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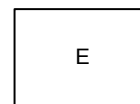


**WLCSP5  
CASE 567AY**

### ELECTRICAL SCHEMATIC



### MARKING DIAGRAM



E = CSPESD304

### ORDERING INFORMATION

| Device    | Package         | Shipping <sup>†</sup> |
|-----------|-----------------|-----------------------|
| CSPESD304 | CSP-5 (Pb-Free) | 3500/Tape & Reel      |

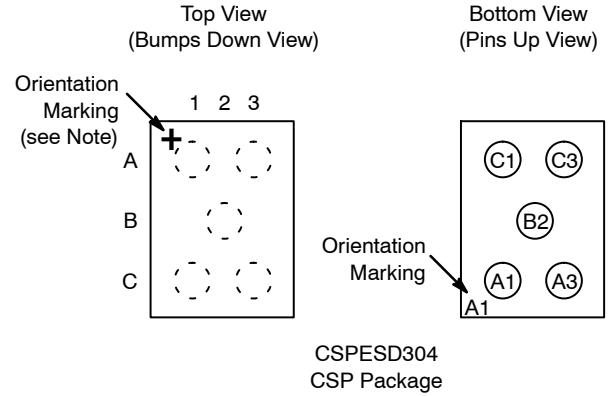
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

# CSPESED304

**Table 1. PIN DESCRIPTIONS**

| 5-bump CSP Package |       |               |
|--------------------|-------|---------------|
| Pin                | Name  | Description   |
| A1                 | ESD_1 | ESD Channel 1 |
| A3                 | ESD_2 | ESD Channel 2 |
| B2                 | GND   | Device Ground |
| C1                 | ESD_3 | ESD Channel 3 |
| C3                 | ESD_4 | ESD Channel 4 |

**PACKAGE / PINOUT DIAGRAMS**



Note: Lead-free devices are specified by using a "+" character for the top side orientation mark.

## SPECIFICATIONS

**Table 2. ABSOLUTE MAXIMUM RATINGS**

| Parameter                 | Rating      | Units |
|---------------------------|-------------|-------|
| Storage Temperature Range | -65 to +150 | °C    |
| DC Package Power Rating   | 200         | mW    |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

**Table 3. STANDARD OPERATING CONDITIONS**

| Parameter                   | Rating     | Units |
|-----------------------------|------------|-------|
| Operating Temperature Range | -40 to +85 | °C    |

**Table 4. ELECTRICAL OPERATING CHARACTERISTICS** (Note 1)

| Symbol      | Parameter  | Conditions                                 | Min                  | Typ         | Max         | Units |
|-------------|--|--|----------------------|-------------|-------------|-------|
| $V_{DIODE}$ | Diode Reverse Breakdown Voltage  | $I_{DIODE} = 10 \mu A$                     | 5.5                  |             |             | V     |
| $I_{LEAK}$  | Diode Leakage Current  | $V_{IN} = 3.3 V, T_A = 25^\circ C$         |                      |             | 100         | nA    |
| $V_{SIG}$   | Signal Voltage<br>Positive Clamp<br>Negative Clamp   | $I_{DIODE} = 10 mA$                        | 5.6<br>-0.4          | 6.8<br>-0.8 | 9.0<br>-1.5 | V     |
| $V_{ESD}$   | In-system ESD Withstand Voltage<br>a) Human Body Model, MIL-STD-883, Method 3015<br>b) Contact Discharge per IEC 61000-4-2 Level 4 | (Note 2)                                   | $\pm 30$<br>$\pm 15$ |             |             | kV    |
| $V_{CL}$    | Clamping Voltage during ESD Discharge<br>MIL-STD-883 (Method 3015), 8 kV<br>Positive Transients<br>Negative Transients             | (Note 2)                                   |                      | +15<br>-8   |             | V     |
| $C_{DIODE}$ | Diode Capacitance  | At 2.5 VDC Reverse Bias,<br>1 MHz, 30 mVAC | 22                   | 27          | 32          | pF    |

- $T_A = -40$  to  $+85^\circ C$  unless otherwise specified.
- ESD applied to input and output pins with respect to GND, one at a time.

PERFORMANCE INFORMATION

Diode Characteristics (nominal conditions unless specified otherwise)

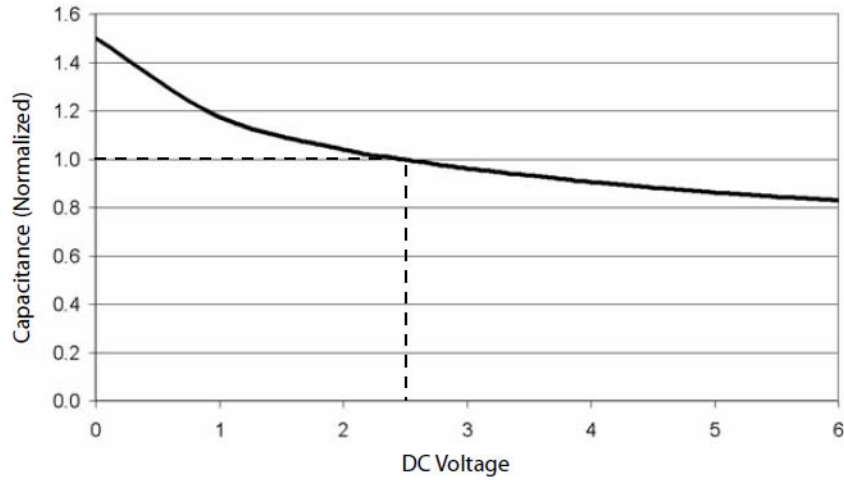


Figure 1. Typical Diode Capacitance vs. Input Voltage (normalized to 2.5 VDC)

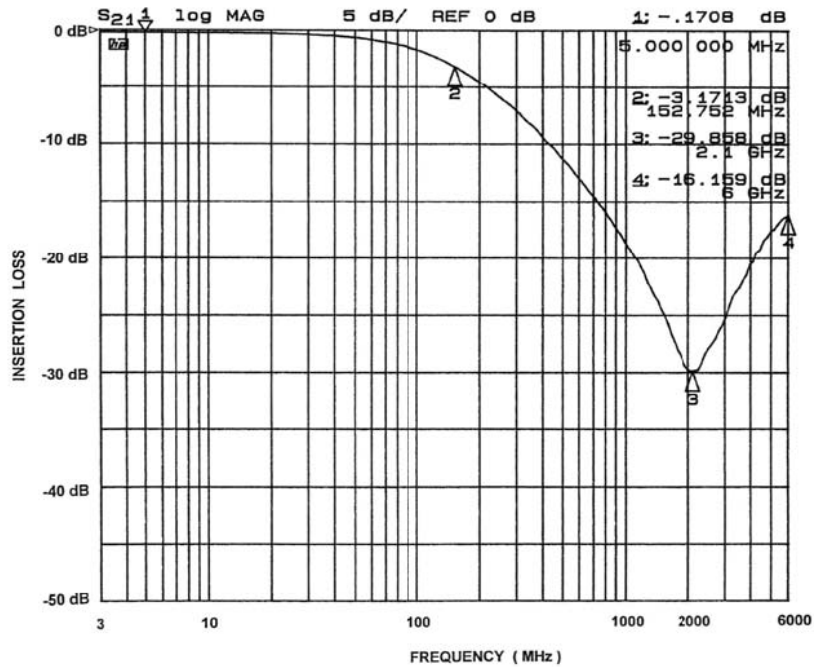


Figure 2. Frequency Response (single channel vs. GND, in 50  $\Omega$  system)

APPLICATION INFORMATION

| Parameter  | Value                        |
|--|------------------------------|
| Pad Size on PCB  | 0.240 mm                     |
| Pad Shape  | Round                        |
| Pad Definition   | Non-Solder Mask defined pads |
| Solder Mask Opening  | 0.290 mm Round               |
| Solder Stencil Thickness   | 0.125 mm – 0.150 mm          |
| Solder Stencil Aperture Opening (laser cut, 5% tapered walls)                      | 0.300 mm Round               |
| Solder Flux Ratio  | 50/50 by volume              |
| Solder Paste Type  | No Clean                     |
| Pad Protective Finish  | OSP (Entek Cu Plus 106A)     |
| Tolerance – Edge To Corner Ball  | $\pm 50 \mu\text{m}$         |
| Solder Ball Side Coplanarity   | $\pm 20 \mu\text{m}$         |
| Maximum Dwell Time Above Liquidous   | 60 seconds                   |
| Maximum Soldering Temperature for Lead-free Devices using a Lead-free Solder Paste | 260°C                        |

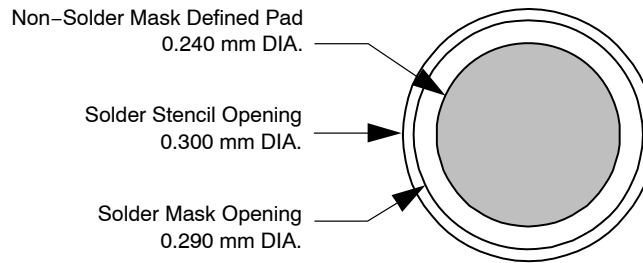


Figure 3. Recommended Non-Solder Mask Defined Pad Illustration

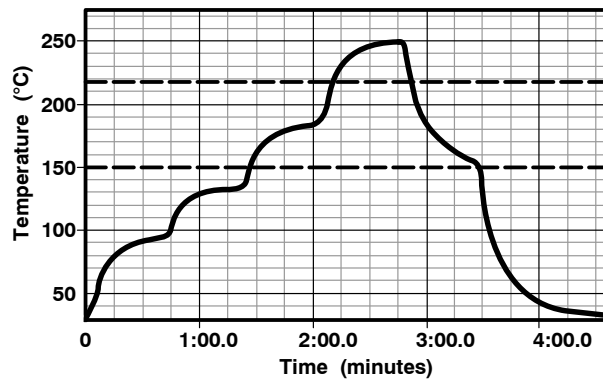


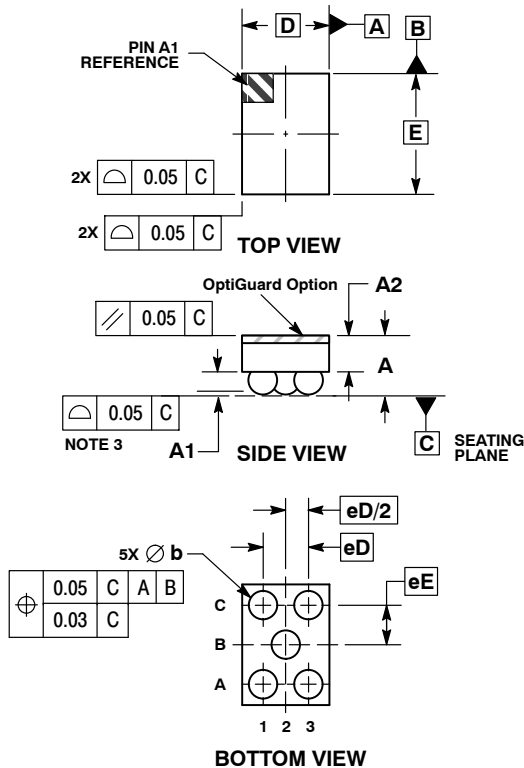
Figure 4. Lead-free (SnAgCu) Solder Ball Reflow Profile



SCALE 4:1

**WLCSP5, 0.96x1.33**  
**CASE 567AY**  
**ISSUE O**

DATE 26 JUL 2010

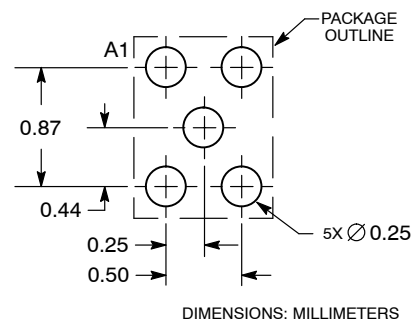


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

| MILLIMETERS |       |      |
|-------------|-------|------|
| DIM         | MIN   | MAX  |
| A           | 0.56  | 0.72 |
| A1          | 0.21  | 0.27 |
| A2          | 0.40  | REF  |
| b           | 0.29  | 0.35 |
| D           | 0.96  | BSC  |
| E           | 1.33  | BSC  |
| eD          | 0.50  | BSC  |
| eE          | 0.435 | BSC  |

**RECOMMENDED  
SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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|-------------------------|--------------------------|--|
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